

## Electrical Leadframes, Surface Mountable Semiconductor Components, Leadframe Strips, and their Method of Manufacture

### **ABSTRACT**

5           The invention relates to a method for producing an electrical leadframe (10), in particular for a light-emitting diode component, having at least one first electrical connection conductor (2) and at least one second electrical connection conductor (3). The method includes a) production of a layer composite comprising an electrically insulating carrier layer (101) and an electrically conductive connection conductor layer (102), b) patterning of the carrier layer (101) in such a way that at least one contact-making window (7) toward the connection conductor layer (102) is produced in said carrier layer, and c) patterning of the connection conductor layer (102), in such a way that the first electrical connection conductor (2) and the second electrical connection conductor (3) are produced, at least one of which can be electrically connected through the contact-making window (7). The invention also relates to a leadframe strip having a connection conductor layer and a connection carrier layer, on which an array with a multiplicity of component regions is formed, the connection conductor layer being at least partly removed along separating lines between two adjacent component regions.